

General SAN KIBISAN® PN-106 L150

Product Description: High clarity

Properties	ISO Test Method	Test Condition	Unit	PN-106 L150
Melt Flow Index	1133	220°C×10KG	ml/10 min	32
Mass Density	1183	23 °C	g/cm ³	1.06
Tensile Strength	527	50 mm/min, yield	MPa	65
		50 mm/min, break	MPa	65
Tensile Elongation	527	50 mm/min	%	3
Flexural Strength	178	2 mm/min	MPa	89
Flexural Modulus		2 mm/min	GPa	2.6
Izod Impact Strength	180/1A	23°C, Notched	KJ/m ²	2
		-30°C, Notched	KJ/m ²	-
Charpy Impact Strength	179	23°C, Notched	KJ/m ²	2
		-30°C, Notched	KJ/m ²	-
Vicat Softening Temp.	306	50°C/hr;1KG	°C	104
		50°C/hr;5KG	°C	101
Heat Distortion Temp.	75/A	1.8MPa, unannealed	°C	88
		1.8MPa, annealed	°C	99
Coefficient of Linear Thermal Expansion	11359	-	-	3.6~3.8*10 ⁻⁵
Flammability	-	UL-94	-	1.5mm HB
Mold Shrinkage	294-4	-	%	0.2~0.7
Symbol	1043	-	-	>SAN<

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Notes: The value provided herein has been established on above test methods and conditions, which only as reference for selecting material, NOT guaranteed values or formal specifications. There can be variation within normal tolerances in colors.

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